ABSTRACT

LEADFRAME AND SEMICONDUCTOR PACKAGE WITH IMPROVED SOLDER JOINT STRENGTH

A semiconductor leadframe and a semiconductor package using same. More particularly, a semiconductor leadframe offering improved solder joint strength between a semiconductor package and a motherboard is disclosed. The leadframe comprises a plate-type frame body; a chip paddle on which a semiconductor chip may be mounted; a plurality of internal leads located radially and spaced at regular intervals about the perimeter of the chip paddle; external leads extending outward from the internal leads and with their terminals connecting to the frame body; and dam bars at the juncture of each external and internal lead for additional support and to ensure that the external leads remain exposed during subsequent encapsulation processes. The leadframe of the present invention providing additional solder joint strength through the use of internal leads having different lengths or surface areas.

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